

DATASHEET

SMD • REFLECTOR 67-03/RSGHBHC-B06/1T



Features

- .P-LCC-4 package.
- .White package and black surface.
- .Optical indicator.
- .Ideal for backlight and light pipe application.
- .Wide viewing angle.
- .Suitable for vapor-phase reflow, Infrared reflow and wave solder processes.
- .Computable with automatic placement equipment.
- .Available on tape and reel (8mm Tape).
- .Pb-free.
- .The product itself will remain with RoHS compliant version

Description

The 67-03 series is available in soft orange, green, blue, and yellow. Due to the package design, the LED has wide viewing angle and optimized light coupling by inter reflector. This feature makes the LED ideal for light pipe application. The low current requirement makes this device ideal for portable equipment or any other application where power is at a premium.



Applications

- .Telecommunication: indicator and backlighting in telephone and fax.
- .Flat backlight for LCD's, switches and symbols.
- .Light pipe application.
- .General use.

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Brilliant Red	
InGaN	Brilliant Green	Water Clear
InGaN	Blue	_

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit	
Reverse Voltage	VR	5	V	
Forward Current	l _F	RS:50 GH:30 BH:30	mA	
Peak Forward Current (Duty 1/10 @1KHz)	I _{FP}	RS:100 GH:100 BH:100	mA	
Power Dissipation	Pd	RS:120 GH:110 BH:110	mW	
Total Power Dissipation	Ptot	340	mW	
Operating Temperature	T_{opr}	-40 ~ +85	$^{\circ}$ C	
Storage Temperature	Tstg	-40 ~ +90	$^{\circ}\mathbb{C}$	
ESD (Classification acc. AEC Q101)	ESDнвм	RS:2000 GH:1000 BH:1000	V	
Soldering Temperature	T _{sol}	Reflow Soldering : 260 $^{\circ}\mathbb{C}$ for 10 sec. Hand Soldering : 350 $^{\circ}\mathbb{C}$ for 3 sec.		



Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbo		Min.	Тур.	Max.	Unit	Condition
		RS	450.0		715.0		
Luminous Intensity	lv	GH	900.0		1420.0	mcd	I _F =20mA
		ВН	225.0		450.0		
Viewing Angle	201/2			120		deg	I _F =20mA
		RS		632			
Peak Wavelength	Λр	GH		518		nm	I _F =20mA
		ВН		468			
		RS	617.0		627.0		
Dominant Wavelength	Λd	GH	520.0		535.0	nm	I _F =20mA
		ВН	465.0		470.0		
Spectrum Padiation		RS		25			
Spectrum Radiation Bandwidth	Δλ	GH		35		nm	I _F =20mA
Dandwidth		ВН		35			
		RS		2.0	2.4		
Forward Voltage	V_{F}	GH		3.5	4.0	V	I _F =20m
		ВН		3.5	4.0		
Reverse Current	IR				10	μA	V _R =5V

Note:

1. Tolerance of Luminous Intensity: ±10%

2. Tolerance of Dominant Wavelength: ±1nm

3. Tolerance of Forward Voltage: ±0.1V



Floating Bin(RS) Bin Range of Luminous Intensity

Symbol	Bin Code	Min.	Max.	Unit	Condition
RS	U1	450.0	565.0	mad	I20m Λ
КS	U2	565.0	715.0	- mcd	I _F =20mA

Bin Range of Dominant Wavelength

Symbol	Bin Code	Min.	Max.	Unit	Condition
RS	1	617.0	622.0	10.100	I_ =ΩΩ ₀₀₀ Λ
K3	2	622.0	627.0	- nm	I _F =20mA

Floating Bin(GH) Bin Range of Luminous Intensity

Symbol	Bin Code	Min.	Max.	Unit	Condition
GH	V2	900.0	1120.0	- mcd	I _F =20mA
OH	W1	1120.0	1420.0	mcu	IF -2011/A

Bin Range of Dominant Wavelength

Symbol	Bin Code	Min.	Max.	Unit	Condition
	X	520.0	525.0		
GH	Υ	525.0	530.0	nm	$I_F = 20mA$
	Z	530.0	535.0	_	

Note:

1. Tolerance of Luminous Intensity: ±10%

2. Tolerance of Dominant Wavelength: ±1nm

3. Tolerance of Forward Voltage: ±0.1V



Floating Bin(BH) Bin Range of Luminous Intensity

Symbol	Bin Code	Min.	Max.	Unit	Condition
	S2	225.0	285.0		
BH	T1	285.0	360.0	mcd	$I_F = 20mA$
	T2	360.0	450.0	_	

Bin Range of Dominant Wavelength

Symbol	Bin Code	Min.	Max.	Unit	Condition
ВН	Χ	465.0	470.0	nm	I _F =20mA

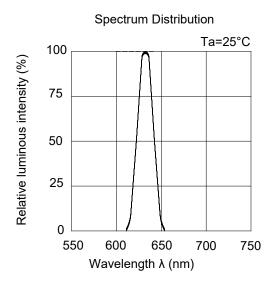
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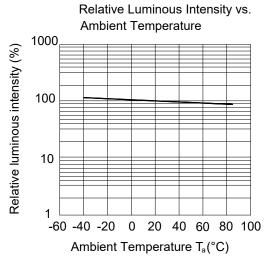
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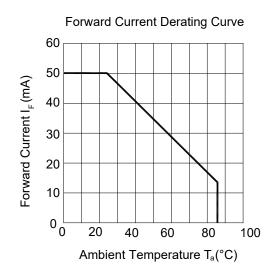
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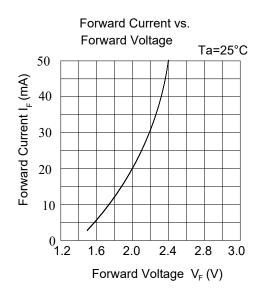
3. Tolerance of Forward Voltage: ±0.1V

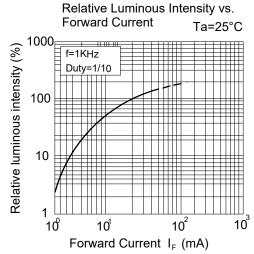
Typical Electro-Optical Characteristics Curves(RS)

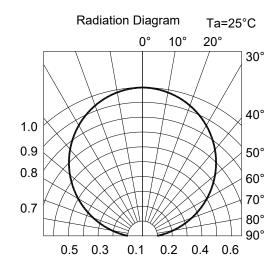




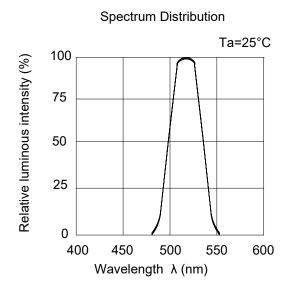


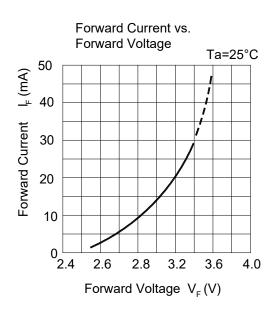


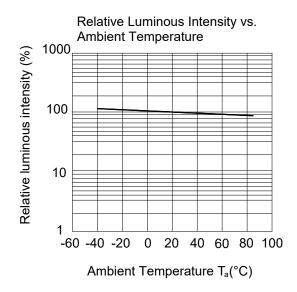


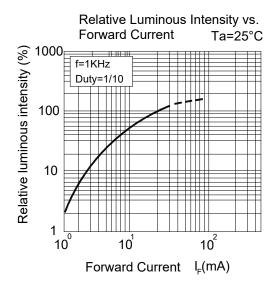


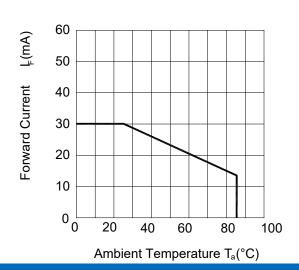
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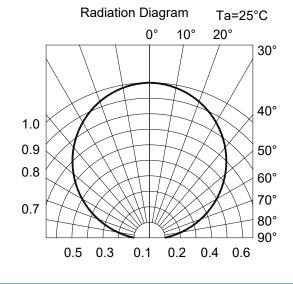




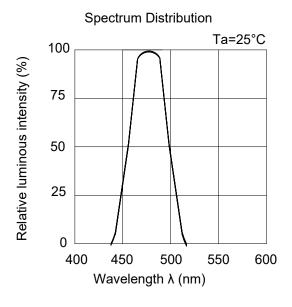


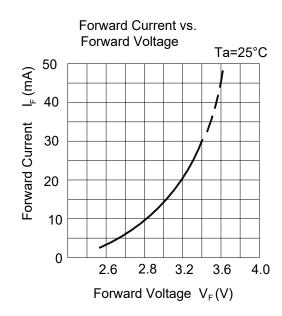


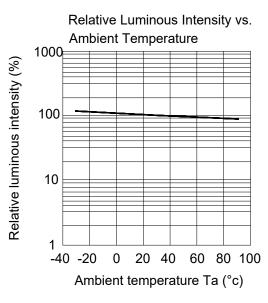


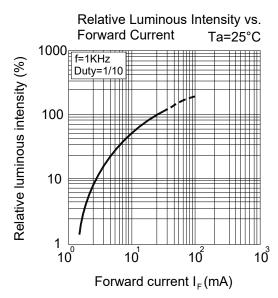


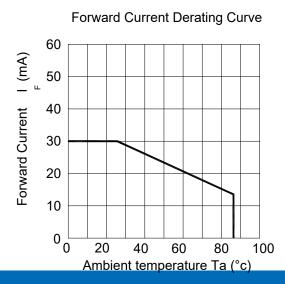
Typical Electro-Optical Characteristics Curves(BH)

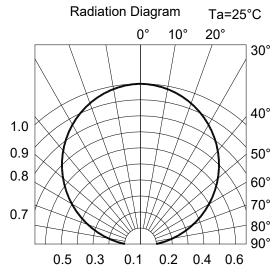




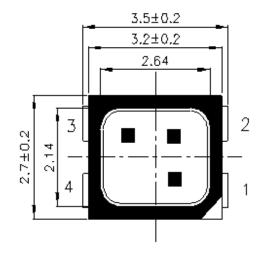


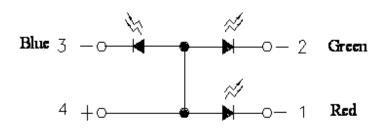


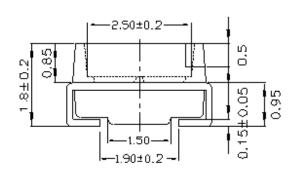


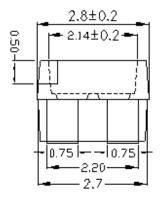


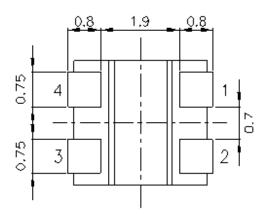
Package Dimension

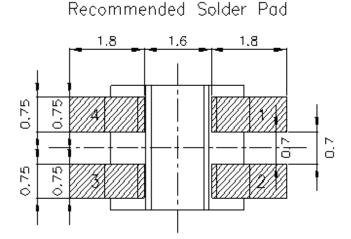








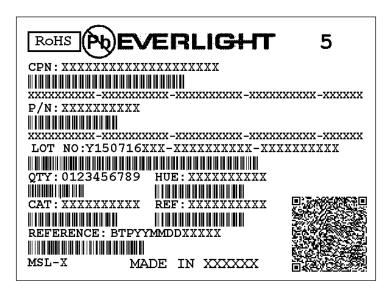




Note: Tolerances unless mentioned ±0.1mm. Unit = mm



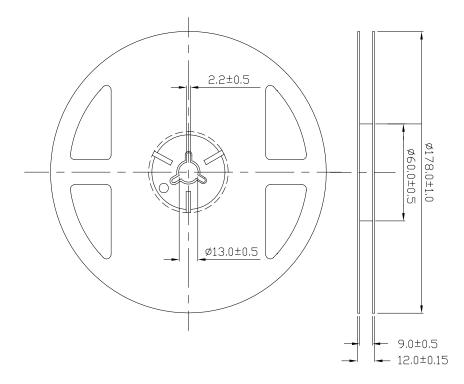
Moisture Resistant Packing Materials



Label Explanation

- · CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- · HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

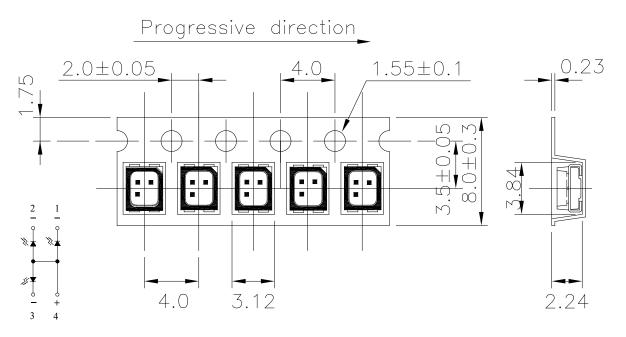
Reel Dimensions



Note: Tolerances unless dimension ± 0.1 mm; Unit = mm

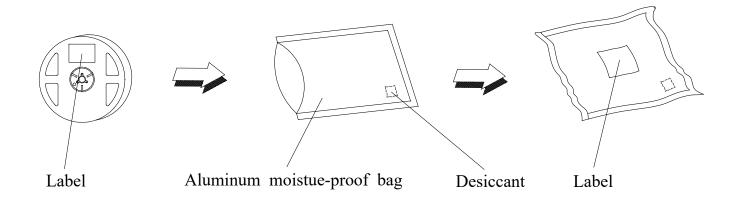
Carrier Tape Dimensions:

Minimum packing amount is 1000 pcs per reel



Note: Tolerances unless mentioned ±0.1mm. Unit = mm

Moisture Resistant Packing Process



Note: Tolerances unless mentioned ±0.1mm. Unit = mm



Precautions for Use

1. Over-current-proof

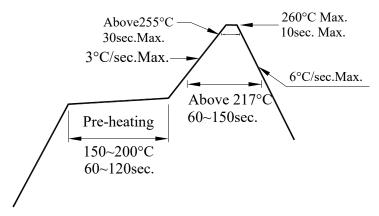
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package: The LEDs should be used within one year and kept at 30°C or less and 70%RH or less.
- 2.3 After opening the package: We recommend that the LED should be soldered quickly (within 3 days). The soldering condition is 30°C or less and 60%RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.Baking treatment: 60±5°C for 24 hours. (One time only)

3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

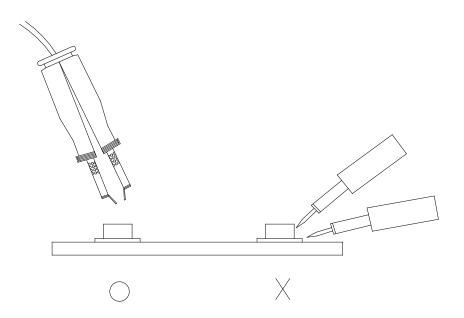


4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.





DISCLAIMER

- 1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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- 6. This product is not intended to be used for military, aircraft, automotive, medical, life sustaining or life saving applications or any other application which can result in human injury or death. Please contact authorized Everlight sales agent for special application request.

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